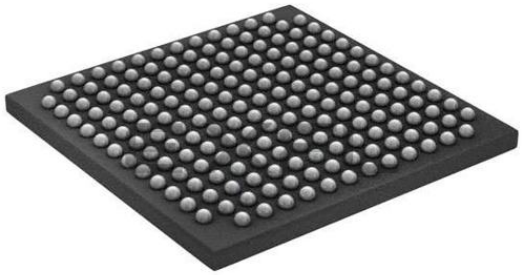

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4F
Core Size	32-Bit Single-Core
Speed	200MHz
Connectivity	CSIO, EBI/EMI, I²C, LINbus, SD, SPI, UART/USART, USB
Peripherals	DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	152
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 32x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	192-LFBGA
Supplier Device Package	192-FBGA (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/s6e2c18j0agb1000a

Debug

- Serial wire JTAG debug port (SWJ-DP)
- Embedded trace macrocells (ETM) provide comprehensive debug and trace facilities.
- AHB trace macrocells (HTM)

Unique ID

Unique value of the device (41-bit) is set.

Power Supply

- Two power supplies
  - Wide range voltage: VCC = 2.7 V to 5.5 V
  - Power supply for VBAT: VBAT = 1.65 V to 5.5 V

4. Pin Descriptions

List of Pin Functions

The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel.

Use the extended port function register (EPFR) to select the pin.

Pin Number				Pin Name	I/O Circuit Type	Pin State Type
LQQ216	LQP176	LQS144	LBE192			
1	1	1	C1	VCC	-	-
2	2	2	B2	PA0 RTO20_0 (PPG20_0) TIOA8_0 AIN2_0 INT00_0 MADATA00_0	G	K
3	3	3	C2	PA1 RTO21_0 (PPG20_0) TIOA9_0 BIN2_0 MADATA01_0	G	I
4	4	4	C3	PA2 RTO22_0 (PPG22_0) TIOA10_0 ZIN2_0 MADATA02_0	G	I
5	5	5	D5	PA3 RTO23_0 (PPG22_0) TIOA11_0 MADATA03_0	G	I
6	6	6	D2	PA4 RTO24_0 (PPG24_0) TIOA12_0 MADATA04_0	G	I
7	7	7	D1	PA5 SIN1_0 RTO25_0 (PPG24_0) TIOA13_0 INT01_0 MADATA05_0	G	K

Pin Number				Pin Name	I/O Circuit Type	Pin State Type
LQQ216	LQP176	LQS144	LBE192			
57	47	39	N3	P41 SOT3_1 (SDA3_1) RTO11_0 (PPG10_0) TIOA1_0 BIN0_0 MCSX6_0	G	I
58	48	40	M3	P42 SCK3_1 (SCL3_1) RTO12_0 (PPG12_0) TIOA2_0 ZIN0_0 MCSX5_0	G	I
59	49	41	L4	P43 SIN15_0 RTO13_0 (PPG12_0) TIOA3_0 INT04_0 MCSX4_0	G	K
60	50	42	M4	P44 SOT15_0 (SDA15_0) RTO14_0 (PPG14_0) TIOA4_0 MCSX3_0	G	I
61	51	43	N4	P45 SCK15_0 (SCL15_0) RTO15_0 (PPG14_0) TIOA5_0 MCSX2_0	G	I
62	52	44	P2	C	-	-
63	53	45	P3	VSS	-	-
64	54	46	P4	VCC	-	-
65	-	-	-	P4A SIN12_1 AIN0_1 INT04_2	E	K
66	-	-	-	P4B SOT12_1 (SDA12_1) BIN0_1	E	I
67	-	-	-	P4C SCK12_1 (SCL12_1) ZIN0_1	E	I
68	-	-	-	P4D SCS72_1 INT05_2	E	K

Pin Number				Pin Name	I/O Circuit Type	Pin State Type
LQQ216	LQP176	LQS144	LBE192			
93	78	62	N10	P77 SCK8_0 (SCL8_0) TIOB5_0 ZIN1_0 MAD06_0	E	I
94	-	-	-	PF8 SCS70_1 DTTI1X_1 AIN1_1	E	I
95	-	-	-	PF9 SCS71_1 IC10_1 BIN1_1	E	I
96	79	63	L10	P78 SIN6_0 IC10_0 INT21_0 MAD07_0	E	K
97	80	64	K10	P79 SOT6_0 (SDA6_0) IC11_0 MAD08_0	L	I
98	81	65	M10	P7A SCK6_0 (SCL6_0) IC12_0 MAD09_0	L	I
99	82	66	N11	P7B DA1 SCS60_0 IC13_0 INT22_0	R	J
100	83	67	M11	P7C DA0 SCS61_0 INT04_1	R	J
101	-	-	-	PFA SCK7_1 (SCL7_1) IC11_1 ZIN1_1	E	I
102	-	-	-	PFB SOT7_1 (SDA7_1) IC12_1 INT07_2	E	K
103	-	-	-	PFC SIN7_1 IC13_1 INT06_2	E	K
104	84	68	N13	PE0 MD1	C	E
105	85	69	N12	MD0	J	D

Pin Number				Pin Name	I/O Circuit Type	Pin State Type
LQQ216	LQP176	LQS144	LBE192			
154	124	100	E12	P24 AN29 TIOA13_1 MAD18_0	F	L
155	125	101	E13	P23 UHCONX1 AN30 SCK0_0 (SCL0_0) TIOB13_1	F	L
156	126	102	D12	P22 AN31 SOT0_0 (SDA0_0) INT26_0	F	M
157	127	103	D13	P21 ADTG_4 SIN0_0 INT27_0 CROUT_0	I	K
158	128	104	C13	P20 NMIX WKUP0	I	F
159	129	105	E14	VCC	-	-
160	130	106	D14	P82 UDM1	H	R
161	131	107	C14	P83 UDP1	H	R
162	132	108	B14	VSS	-	-
163	133	109	A13	VCC	-	-
164	134	110	B13	P00 TRSTX	E	G
165	135	111	A12	P01 TCK SWCLK	E	G
166	136	112	C12	P02 TDI	E	G
167	137	113	B12	P03 TMS SWDIO	E	G
168	138	114	B11	P04 TDO SWO	E	G
169	139	-	C11	P90 INT12_1 Q_IO3_0	S	K
170	140	-	D11	P91 SIN5_1 INT13_1 Q_IO2_0	S	K
171	141	-	B10	P92 SOT5_1 (SDA5_1) INT14_1 Q_IO1_0	S	K

Pin Number				Pin Name	I/O Circuit Type	Pin State Type
LQQ216	LQP176	LQS144	LBE192			
194	162	132	E7	PCF RTS4_1 INT12_0	L	K
195	163	133	F7	PD0 INT30_1	L	K
196	164	134	B6	PD1 INT31_1	L	K
197	165	135	C6	PD2 CTS4_1 FRCK2_1	L	I
198	166	136	D6	P6E ADTG_5 SCK4_1 (SCL4_1) IC23_1 INT29_0	E	K
199	-	-	-	P6D SCK14_1 (SCL14_1) IC22_1 TIOB6_2	E	I
200	-	-	-	P6C SOT14_1 (SDA14_1) IC21_1 TIOA6_2	E	I
201	-	-	-	P6B SIN14_1 IC20_1 TIOB7_2 INT14_2	E	K
202	-	-	-	P6A DTTI2X_1 TIOA7_2	E	I
203	-	-	-	P69 RTO20_1 (PPG20_1) TIOB14_2	E	I
204	-	-	-	P68 SCK13_1 (SCL13_0) RTO21_1 (PPG20_1) TIOA14_2	E	I
205	-	-	-	P67 SOT13_1 (SDA13_1) RTO22_1 (PPG22_1) TIOB15_2	E	I
206	-	-	-	P66 SIN13_1 RTO23_1 (PPG22_1) TIOA15_2 INT15_2	E	K

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
Multi-Function Timer 1	DTTI1X_0	Input signal controlling waveform generator outputs RTO10 to RTO15 of Multi-Function Timer 1.	70	55	47	L5
	DTTI1X_1		94	-	-	-
	FRCK1_0	16-bit free-run timer ch 1 external clock input pin	71	56	48	M5
	FRCK1_1		78	63	-	K5
	IC10_0	16-bit input capture input pin of Multi-Function Timer 1. ICxx describes channel number.	96	79	63	L10
	IC10_1		95	-	-	-
	IC11_0		97	80	64	K10
	IC11_1		101	-	-	-
	IC12_0		98	81	65	M10
	IC12_1		102	-	-	-
	IC13_0		99	82	66	N11
	IC13_1		103	-	-	-
	RTO10_0 (PPG10_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG10 when it is used in PPG1 output modes.	56	46	38	N2
	RTO10_1 (PPG10_1)		85	70	-	N8
	RTO11_0 (PPG10_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG10 when it is used in PPG1 output modes.	57	47	39	N3
	RTO11_1 (PPG10_1)		86	71	-	M8
	RTO12_0 (PPG12_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG12 when it is used in PPG1 output modes.	58	48	40	M3
	RTO12_1 (PPG12_1)		87	72	-	N9
	RTO13_0 (PPG12_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG12 when it is used in PPG1 output modes.	59	49	41	L4
	RTO13_1 (PPG12_1)		88	73	-	P9
	RTO14_0 (PPG14_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG14 when it is used in PPG1 output modes.	60	50	42	M4
	RTO14_1 (PPG14_1)		89	74	-	M9
	RTO15_0 (PPG14_0)	Waveform generator output pin of Multi-Function Timer 1. This pin operates as PPG14 when it is used in PPG1 output modes.	61	51	43	N4
	RTO15_1 (PPG14_1)		90	75	-	L9

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
Real-time clock	RTCCO_0	0.5 seconds pulse output pin of real-time clock	211	171	139	C4
	RTCCO_1		33	-	-	-
	SUBOUT_0	Sub-clock output pin	211	171	139	C4
	SUBOUT_1		33	-	-	-
Low power Consump-tion mode	WKUP0	Deep Standby mode return signal input pin 0	158	128	104	C13
	WKUP1	Deep Standby mode return signal input pin 1	14	13	10	E5
	WKUP2	Deep Standby mode return signal input pin 2	70	55	47	L5
	WKUP3	Deep Standby mode return signal input pin 3	212	172	140	B3
D/A converter	DA0	D/A converter ch 0 analog output pin	100	83	67	M11
	DA1	D/A converter ch 1 analog output pin	99	82	66	N11
VBAT	VREGCTL	On-board regulator control pin	76	61	53	N6
	VWAKEUP	The return signal input pin from a hibernation state	77	62	54	M6
SD I/F	S_CLK_0	SD memory card interface SD memory card clock output pin	38	28	23	H3
	S_CMD_0	SD memory card interface SD memory card command output	41	31	26	H6
	S_DATA1_0	SD memory card interface SD memory card data bus	36	26	21	H2
	S_DATA0_0		37	27	22	J1
	S_DATA3_0		42	32	27	J5
	S_DATA2_0		43	33	28	J4
	S_CD_0	SD memory card interface SD memory card detection pin	45	35	30	J2
	S_WP_0	SD memory card interface SD memory card write protection	44	34	29	J3
I^2S	I2SMCLK0_0	I^2S external clock pin	51	41	-	L2
	I2SDO0_0	I^2S serial transition data output pin	52	42	-	L3
	I2SWS0_0	I^2S frame synchronization signal pin	53	43	-	M2
	I2SDI0_0	I^2S serial received data input pin	34	24	-	G6
	I2SCK0_0	I^2S bit clock pin	35	25	-	H4
High-speed quad SPI	Q_SCK_0	SPI clock output pin	173	143	-	D10
	Q_IO0_0	SPI data input/output pin	172	142	-	C10
	Q_IO1_0		171	141	-	B10
	Q_IO2_0		170	140	-	D11
	Q_IO3_0		169	139	-	C11
	Q_CS0_0	SPI chip select output pin	174	144	-	B9
	Q_CS1_0		175	-	-	-
	Q_CS2_0		176	-	-	-

Surface Mount Type

Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges.

You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

Lead-Free Packaging

CAUTION: When ball grid array (BGA) packages with Sn-Ag-Cu balls are mounted using Sn-Pb eutectic soldering, junction strength may be reduced under some conditions of use.

Storage of Semiconductor Devices

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent this, do the following:

1. Avoid exposure to rapid temperature changes, which can cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
2. Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between 5°C and 30°C.
3. When Dry Packages are opened, it is recommended to have humidity between 40% and 70%.
4. When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in these aluminum laminate bags for storage.
5. Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

Baking

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

Condition: 125°C/24 h

Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

1. Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.
2. Electrically ground all conveyors, solder vessels, soldering irons, and peripheral equipment.
3. Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 MΩ). Wearing of conductive clothing and shoes, and the use of conductive floor mats and other measures to minimize shock loads is recommended.
4. Ground all fixtures and instruments, or protect with anti-static measures.
5. Avoid the use of Styrofoam or other highly static-prone materials for storage of completed board assemblies.

12.3.2 Pin Characteristics

(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
H level input voltage (hysteresis input)	V_{IHS}	CMOS hysteresis input pin, MD0, MD1	-	V_{CC}×0.8	-	V_{CC} + 0.3	V	
		MADATAxx	V_{CC} > 3.0 V, V_{CC} ≤ 3.6 V,	2.4	-	V_{CC} + 0.3	V	At External Bus
		5V tolerant input pin	-	V_{CC}×0.8	-	V_{SS} + 5.5	V	
		Input pin doubled as I^2C Fm+	-	V_{CC}×0.7	-	V_{SS} + 5.5	V	
		TTL Schmitt input pin	-	2.0	-	V_{CC}+0.3	V	
L level input voltage (hysteresis input)	V_{ILS}	CMOS hysteresis input pin, MD0, MD1	-	V_{SS} - 0.3	-	V_{CC}×0.2	V	
		5V tolerant input pin	-	V_{SS} - 0.3	-	V_{CC}×0.2	V	
		Input pin doubled as I^2C Fm+	-	V_{SS}	-	V_{CC}×0.3	V	
		TTL Schmitt input pin	-	V_{SS} - 0.3	-	0.8	V	
H level output voltage	V_{OH}	4 mA type	V_{CC} ≥ 4.5 V, I_{OH} = - 4 mA	V_{CC} - 0.5	-	V_{CC}	V	
			V_{CC} < 4.5 V, I_{OH} = - 2 mA					
		8 mA type	V_{CC} ≥ 4.5 V, I_{OH} = - 8 mA	V_{CC} - 0.5	-	V_{CC}	V	
			V_{CC} < 4.5 V, I_{OH} = - 4 mA					
		10 mA type	V_{CC} ≥ 4.5 V, I_{OH} = - 10 mA	V_{CC} - 0.5	-	V_{CC}	V	
			V_{CC} < 4.5 V, I_{OH} = - 8 mA					
		12 mA type	V_{CC} ≥ 4.5 V, I_{OH} = - 12 mA	V_{CC} - 0.5	-	V_{CC}	V	
			V_{CC} < 4.5 V, I_{OH} = - 8 mA					
		The pin doubled as I^2C Fm+	V_{CC} ≥ 4.5 V, I_{OH} = - 4 mA	V_{CC} - 0.5	-	V_{CC}	V	At GPIO
			V_{CC} < 4.5V, I_{OH} = - 3 mA					

12.4.10 External Bus Timing

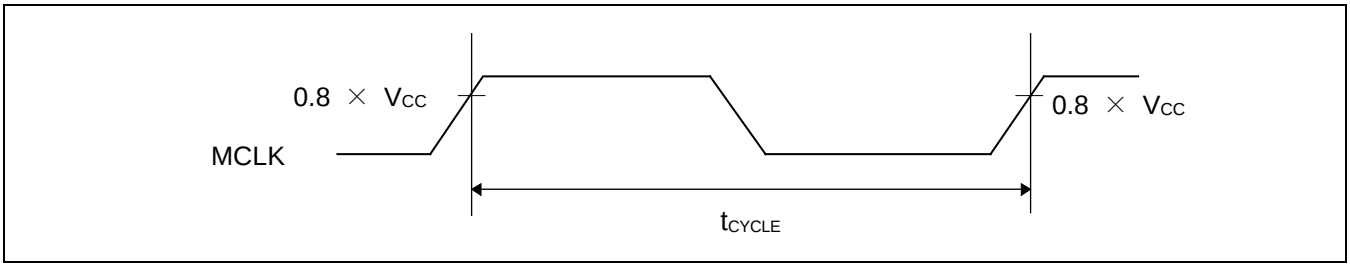
External Bus Clock Output Characteristics

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Typ		
Output frequency	t_{CYCLE}	MCLKOUT *1		-	50 *2	MHz	

1: The external bus clock (MCLKOUT) is a divided clock of HCLK.

For more information about setting of clock divider, see Chapter 14: External Bus Interface in FM4 Family Peripheral Manual Main Part (002-04856).

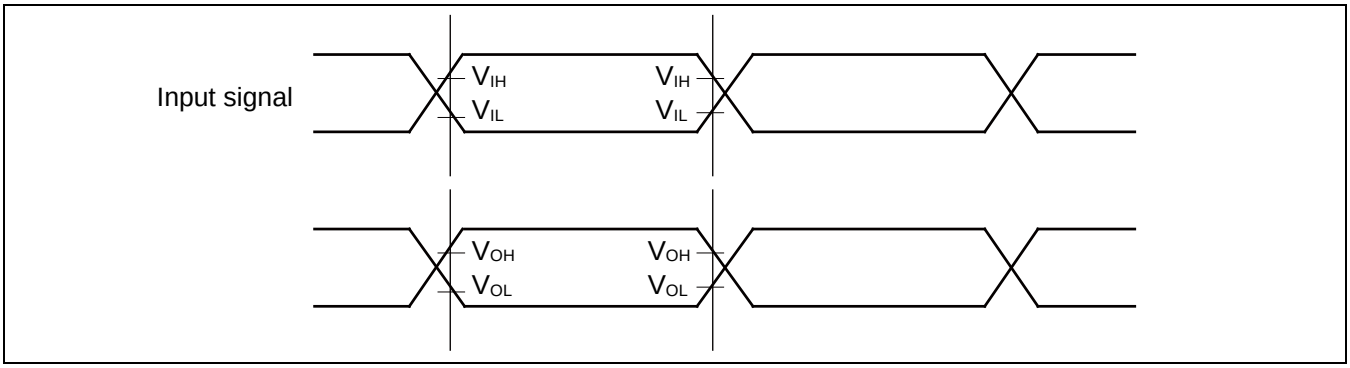
2: Generate MCLKOUT at setting more than four divisions when the AHB bus clock exceeds 100 MHz.



External Bus Signal I/O Characteristics

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	Value	Unit	Remarks
Signal input characteristics	V_{IH}	-	0.8 × V_{CC}	V	
	V_{IL}		0.2 × V_{CC}	V	
Signal output characteristics	V_{OH}		0.8 × V_{CC}	V	
	V_{OL}		0.2 × V_{CC}	V	



Synchronous Serial (SPI = 1, SCINV = 1)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
				Min	Max	Min	Max	
Baud rate	-	-	-	-	8	-	8	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Internal shift clock operation	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK↓→SOT delay time	t_{SLOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN→SCK↑ setup time	t_{IVSHI}	SCKx, SINx		50	-	30	-	ns
SCK↑→SIN hold time	t_{SHIXI}	SCKx, SINx		0	-	0	-	ns
SOT→SCK↑ delay time	t_{SOVHI}	SCKx, SOTx		$2t_{CYCP}$ - 30	-	$2t_{CYCP}$ - 30	-	ns
Serial clock L pulse width	t_{SLSH}	SCKx	External shift clock operation	$2t_{CYCP}$ - 10	-	$2t_{CYCP}$ - 10	-	ns
Serial clock H pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK↓→SOT delay time	t_{SLOVE}	SCKx, SOTx		-	50	-	30	ns
SIN→SCK↑ setup time	t_{IVSHE}	SCKx, SINx		10	-	10	-	ns
SCK↑→SIN hold time	t_{SHIXE}	SCKx, SINx		20	-	20	-	ns
SCK fall time	t_F	SCKx		-	5	-	5	ns
SCK rise time	t_R	SCKx		-	5	-	5	ns

Notes:

- *The above characteristics apply to CLK synchronous mode.*
- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 8. Block Diagram in this data sheet.*
- *These characteristics only guarantee the same relocate port number; for example, the combination of SCKx_0 and SOTx_1 is not guaranteed.*
- *When the external load capacitance C_L = 30 pF.*

When Using Synchronous Serial Chip Select (SCINV = 0, CSLVL = 0)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
			Min	Max	Min	Max	
SCS↑→SCK↓ setup time	t_{CSSI}	Internal shift clock operation	(*1)-50	(*1)+0	(*1)-50	(*1)+0	ns
SCK↑→SCS↓ hold time	t_{CSHI}		(*2)+0	(*2)+50	(*2)+0	(*2)+50	ns
SCS deselect time	t_{CSDI}		(*3)-50 +5t_{CYCP}	(*3)+50 +5t_{CYCP}	(*3)-50 +5t_{CYCP}	(*3)+50 +5t_{CYCP}	ns
SCS↑→SCK↓ setup time	t_{CSSE}	External shift clock operation	3t_{CYCP}+30	-	3t_{CYCP}+30	-	ns
SCK↑→SCS↓ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		3t_{CYCP}+30	-	3t_{CYCP}+30	-	ns
SCS↑→SOT delay time	t_{DSE}		-	40	-	40	ns
SCS↓→SOT delay time	t_{DEE}		0	-	0	-	ns

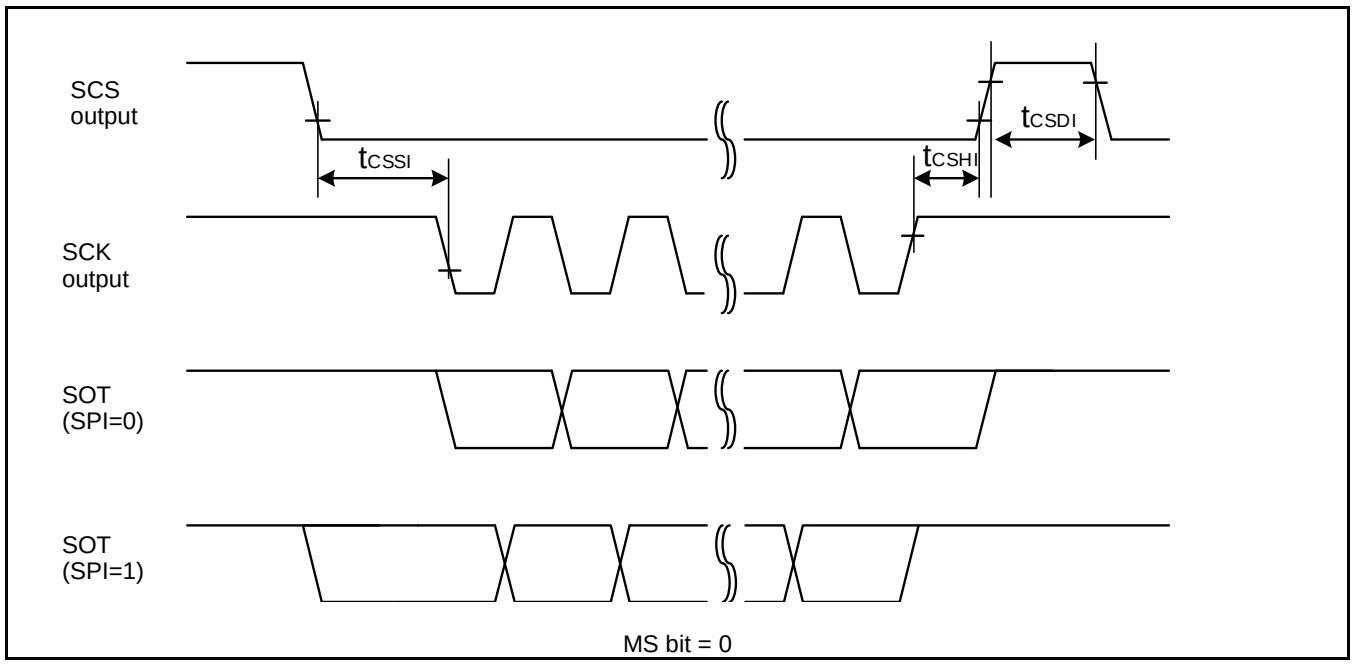
(*1): CSSU bit value×serial chip select timing operating clock cycle [ns]

(*2): CSHD bit value×serial chip select timing operating clock cycle [ns]

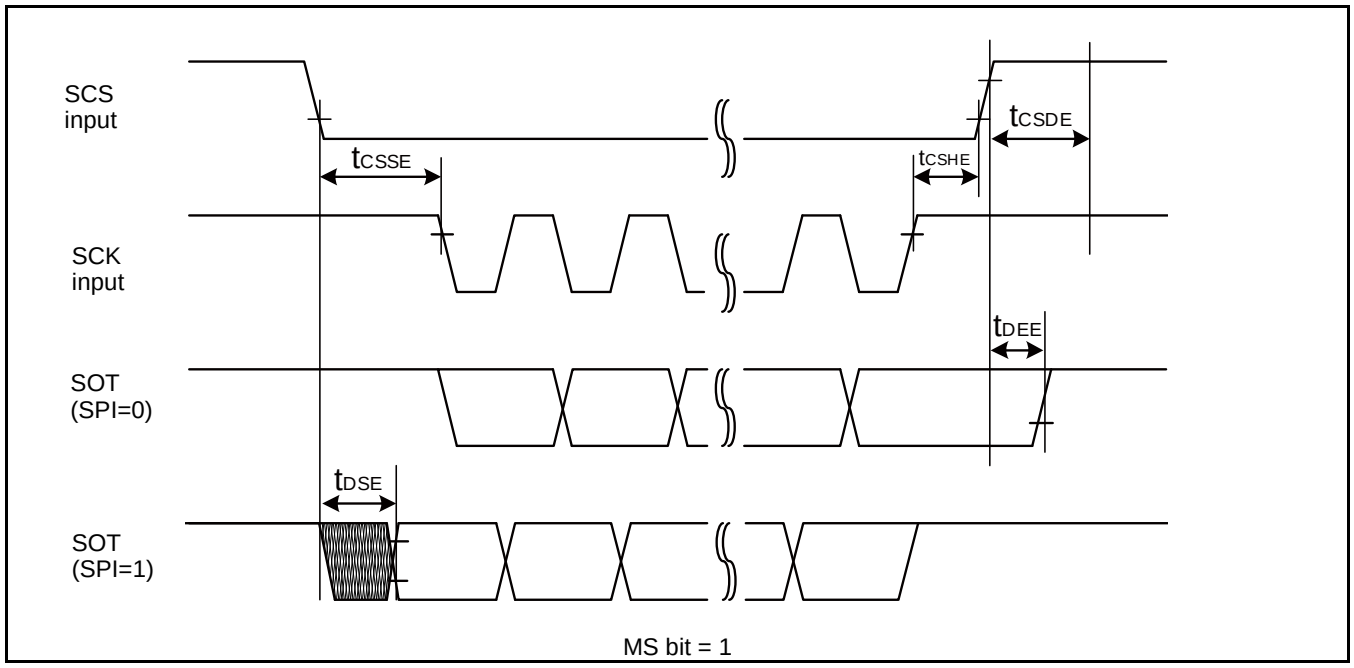
(*3): CSDS bit value×serial chip select timing operating clock cycle [ns]

Notes:

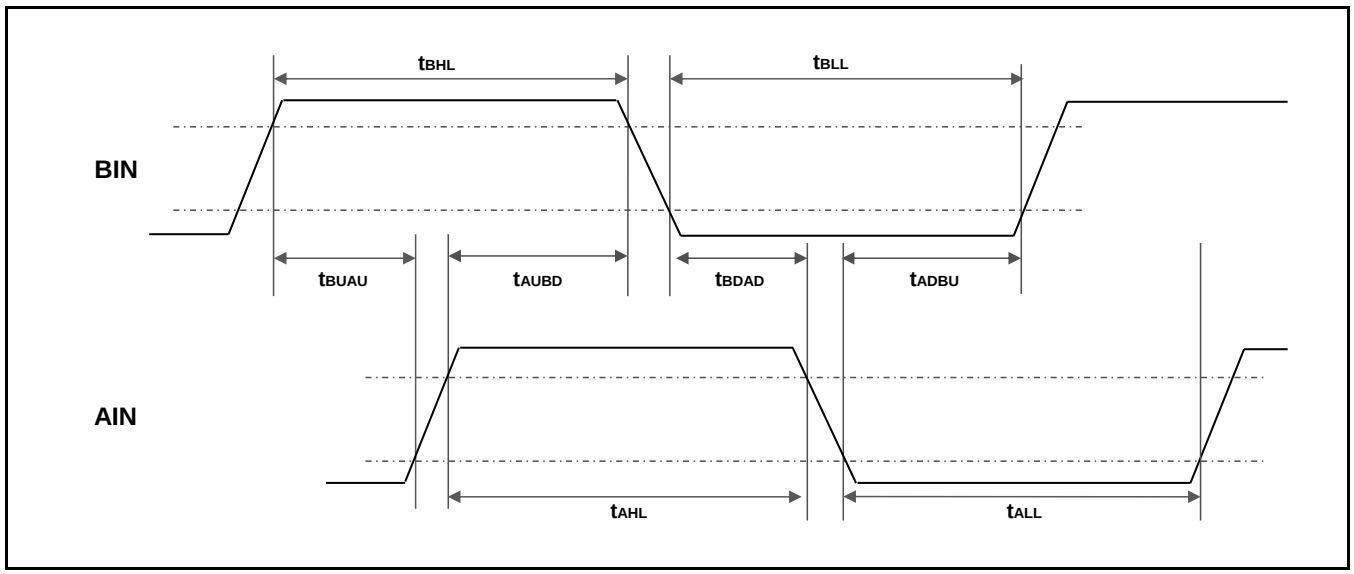
- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 8. Block Diagram in this data sheet.*
- *For more information about CSSU, CSHD, CSDS, and the serial chip select timing operating clock, see FM4 Family Peripheral Manual Main Part (002-04856).*
- *When the external load capacitance C_L = 30 pF.*

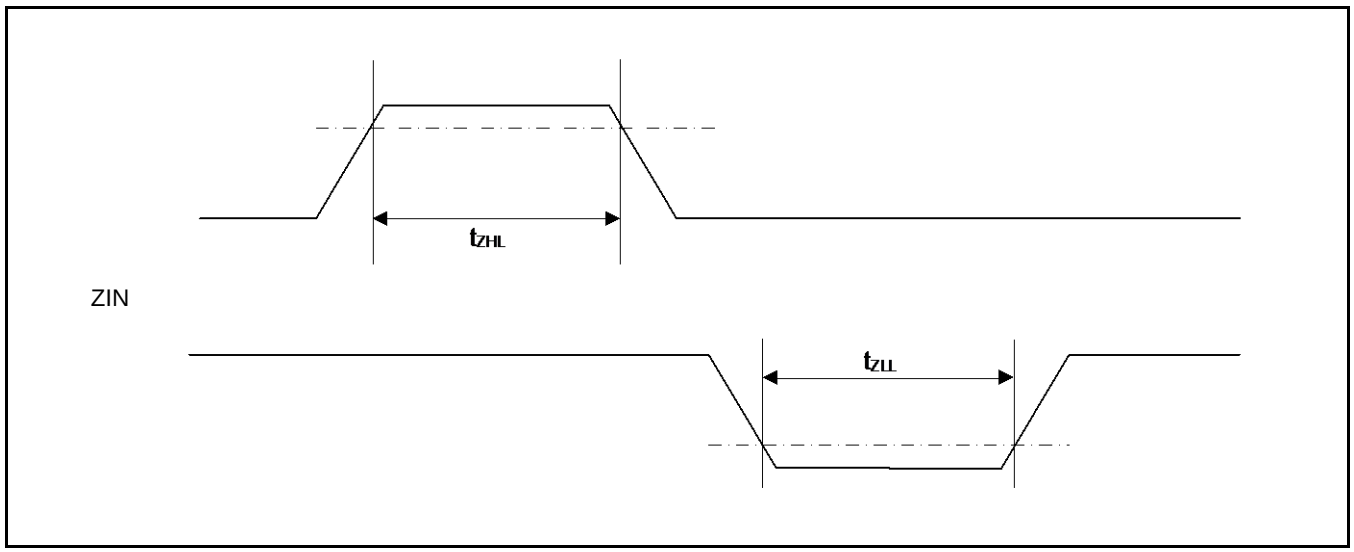


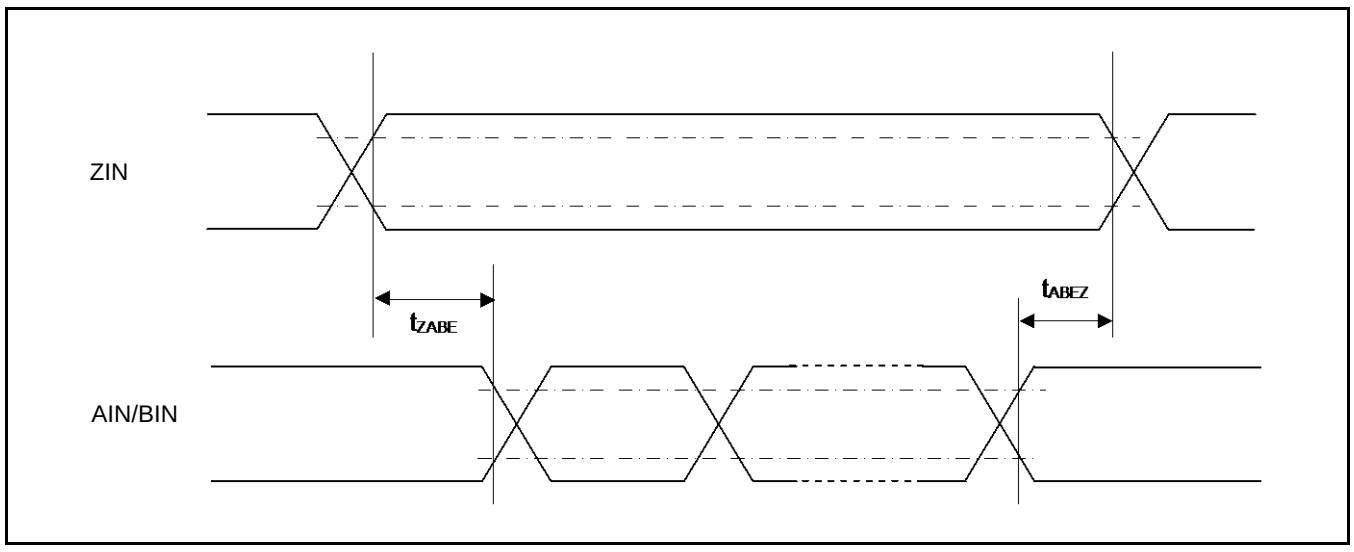
MS bit = 0



MS bit = 1


BIN
AIN
tBHL
tBLL
tBUAU
tAUBD
tBDAD
tADBU
tAHL
tALL


ZIN
tZHL
tZLL


ZIN
AIN/BIN
tZABE
tABEZ

12.4.20 High-Speed Quad SPI Timing

(V_{CC} = 2.7V to 3.6V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Serial clock frequency	t_{SCYCM}	Q_SCK_0	C_L = 15 pF, V_{CC} = 3.0 to 3.6V	-	66	MHz	*1
			C_L = 30 pF	-	50	MHz	*2
Enabled CS→ CLK Starting Time (mode0/mode2)	$t_{OSLSK02}$	Q_SCK_0, Q_CS0_0, Q_CS1_0, Q_CS2_0	C_L = 30 pF	1.5 × t_{SCYCM} - 5	-	ns	
Enabled CS→ CLK Starting Time (mode1/mode3)	$t_{OSLSK13}$			t_{SCYCM} - 5	-	ns	
CLK Last→ Disabled CS Time (mode0/mode2)	$t_{OSKSL02}$			t_{SCYCM}	-	ns	
CLK Last→ Disabled CS Time (mode1/mode3)	$t_{OSKSL13}$			1.5 × t_{SCYCM}	-	ns	
SIO Data output time	t_{OSDAT}	Q_SCK_0, Q_IO0_0, Q_IO1_0, Q_IO2_0, Q_IO3_0	C_L = 15 pF, V_{CC} = 3.0 to 3.6V	0	5	ns	
			C_L = 30 pF	0	5		
SIO Setup	t_{DSSET}		C_L = 30 pF	3	-	ns	*1
				10	-		*2
SIO Hold	t_{SDHOLD}		C_L = 30 pF	0.5 × t_{SCYCM}	-	ns	

1: When RTM = 1 and mode = 0, 1, 3

2: When RTM = 1 and mode = 2 or RTM = 0 and mode = 0, 1, 2, 3

Notes:

- *See Chapter 8-3: High-Speed Quad SPI controller in FM4 Family Peripheral Manual Communication Macro Part (002-04862) for the detail of RTM mode.*
- *When using High-Speed Quad SPI, please set PDSR register to set the pin drive capability for V_{CC} = 3 V. See Chapter 12: I/O Port in FM4 Family Peripheral Manual Main Part (002-04856) for the details.*

12.6 12-bit D/A Converter

Electrical Characteristics for the D/A Converter

(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V)

Parameter	Symbol	Pin Name	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	-	DAx	-	-	12	bit	
Conversion time	t_{C20}		0.56	0.69	0.81	µs	Load 20 pF
	t_{C100}		2.79	3.42	4.06	µs	Load 100 pF
Integral nonlinearity*	INL		- 16	-	+ 16	LSB	
Differential nonlinearity*	DNL		- 0.98	-	+ 1.5	LSB	
Output voltage offset	V_{OFF}		-	-	+ 10	mV	When setting 0x000
			- 20.0	-	+ 1.4	mV	When setting 0xFFF
Analog output impedance	R_O		3.10	3.80	4.50	kΩ	D/A operation
			2.0	-	-	MΩ	When D/A stop
Power supply current*	IDDA	AVCC	260	330	410	µs	D/A 1ch operation AV_{CC} = 3.3 V
			400	510	620	µs	D/A 1ch operation AV_{CC} = 5.0 V
	IDSA		-	-	14	µs	When D/A stop

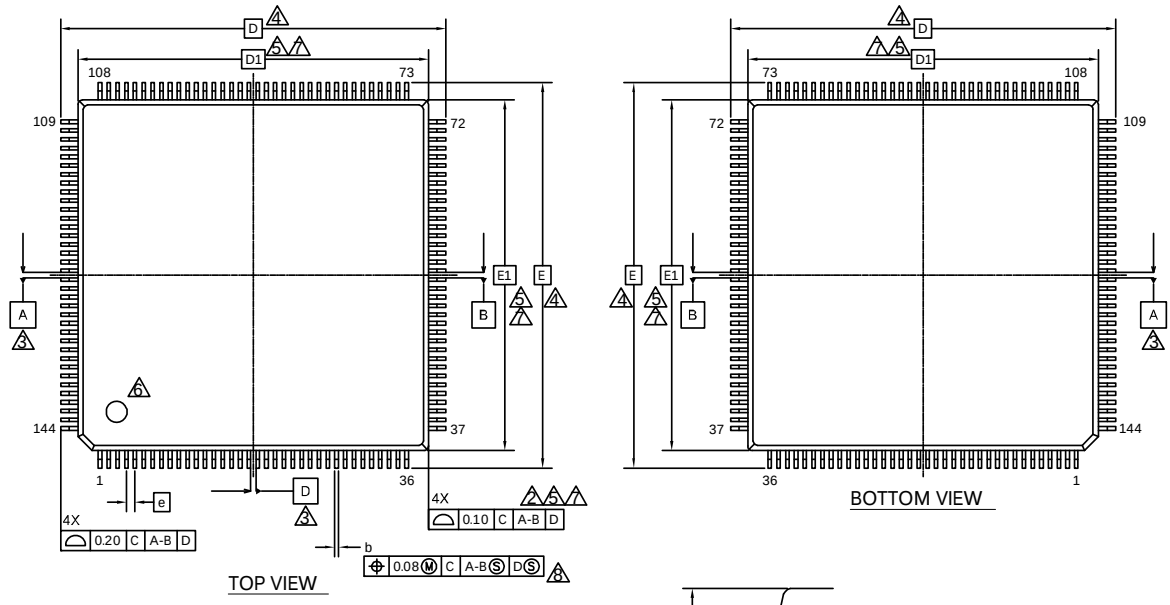
*: During no load

13. Ordering Information

Part number	Flash	RAM	Crypto	Package
S6E2C18H0AGV2000A	1 MB	128 KB	N/A	Plastic・LQFP (0.5-mm pitch), 144 pin (LQS144)
S6E2C19H0AGV2000A	1.5 MB	192 KB	N/A	
S6E2C1AH0AGV2000A	2 MB	256 KB	N/A	
S6E2C18J0AGV2000A	1 MB	128 KB	N/A	Plastic・LQFP (0.65-mm pitch), 176 pin (LQP176)
S6E2C19J0AGV2000A	1.5 MB	192 KB	N/A	
S6E2C1AJ0AGV2000A	2 MB	256 KB	N/A	
S6E2C18J0AGB1000A	1 MB	128 KB	N/A	Plastic・LQFP (0.8-mm pitch), 192 pin (LBE192)
S6E2C19J0AGB1000A	1.5 MB	192 KB	N/A	
S6E2C1AJ0AGB1000A	2 MB	256 KB	N/A	
S6E2C18L0AGL2000A	1 MB	128 KB	N/A	Plastic・LQFP (0.4-mm pitch), 216 pin (LQQ216)
S6E2C19L0AGL2000A	1.5 MB	192 KB	N/A	
S6E2C1AL0AGL2000A	2 MB	256 KB	N/A	

14. Package Dimensions

Package Type	Package Code
LQFP 144	LQS 144



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.00	—	0.20
b	0.17	0.22	0.27
c	0.09	—	0.20
D	22.00 BSC		
D1	20.00 BSC		
e	0.50 BSC		
E	22.00 BSC		
E1	20.00 BSC		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70

NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

002-13015 **

PACKAGE OUTLINE, 144 LEAD LQFP
20.0X20.0X1.7 MM LQS144 Rev**

Document History

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Document Number: 002-05032

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	-	AKIH	04/22/2015	New Spec.
*A	5126421	HITK	02/05/2016	Company name and layout design change. Added the note of TAP pin. Updated Package Code and Dimensions (LQFP-144, LQFP-176, LQFP-216).
*B	5634625	YSKA	02/20/2017	Deleted USB, CAN in communications interfaces.(Page 1) Deleted USB, CAN related pins and VDDs. Updated LQS144, LQP176, LQQ216 pin assignments schematics (Page 11-13) Updated 12.4.8 Power-On Reset Timing. Changed parameter from “Power Supply rise time (t_{VCCR})[ms]” to “Power ramp rate (dV/dt)[mV/us]” and add some comments. (Page 112) Modified CSIO timing typo (12.4.12 CSIO(SPI) Timing) Deleted “SPI=1, MS=0” in the titles and added MS=0,1 in the schematic(Page 133-140, 149-156) Modified RTC description(Features, Real-Time Clock(RTC)) Changed starting count value from 01 to 00. Deleted “second , or day of the week” in the Interrupt function.(Page 3) Modifications related to the VBAT in the following chapter. “7. Handling Devices” Notes on Power-on (Page 76) “11. Pin Status in Each CPU State” List of VBAT Domain Pin Status (Page 90) “12.3.1 Current Rating” Table12-9. Typical and Maximum Current Consumption in Deep Standby STOP Mode, Deep Standby RTC Mode and VBAT (Page 104) Deleted MPNs below from “13. Ordering Information” (Page 184) S6E2C18H0AGV20000, S6E2C19H0AGV20000, S6E2C1AH0AGV20000, S6E2C18J0AGV20000, S6E2C19J0AGV20000, S6E2C1AJ0AGV20000, S6E2C18J0AGB10000, S6E2C19J0AGB10000, S6E2C1AJ0AGB10000, S6E2C18L0AGL20000, S6E2C19L0AGL20000, S6E2C1AL0AGL20000 Added MPNs below to “13. Ordering Information” (Page 184) S6E2C18H0AGV2000A, S6E2C19H0AGV2000A, S6E2C1AH0AGV2000A, S6E2C18J0AGV2000A, S6E2C19J0AGV2000A, S6E2C1AJ0AGV2000A, S6E2C18J0AGB1000A, S6E2C19J0AGB1000A, S6E2C1AJ0AGB1000A, S6E2C18L0AGL2000A, S6E2C19L0AGL2000A, S6E2C1AL0AGL2000A Deleted Baud rate spec for High-Speed Synchronous Serial in “12.4.12 CSIO(SPI) Timing”(Page 141-147) Modified the expression of the “Built-in CR” and add Note in the “1. Product Lineup”(Page 8) Modified typo(SCLKx_0 -> SCKx_0)(Page 125, 127, 129, 131) Added Maximum Access size in “Features”(Page 1) Updated IO circuit (type A) (Page 62)